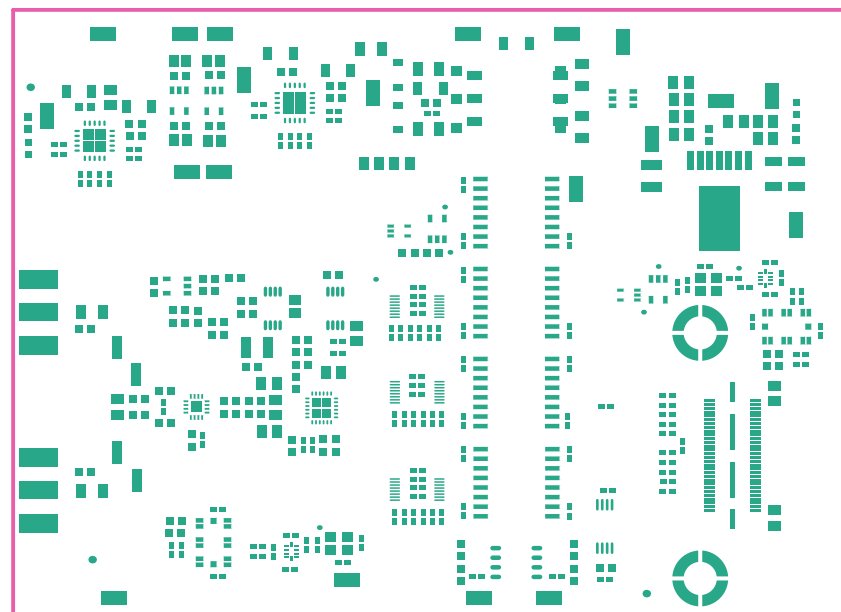
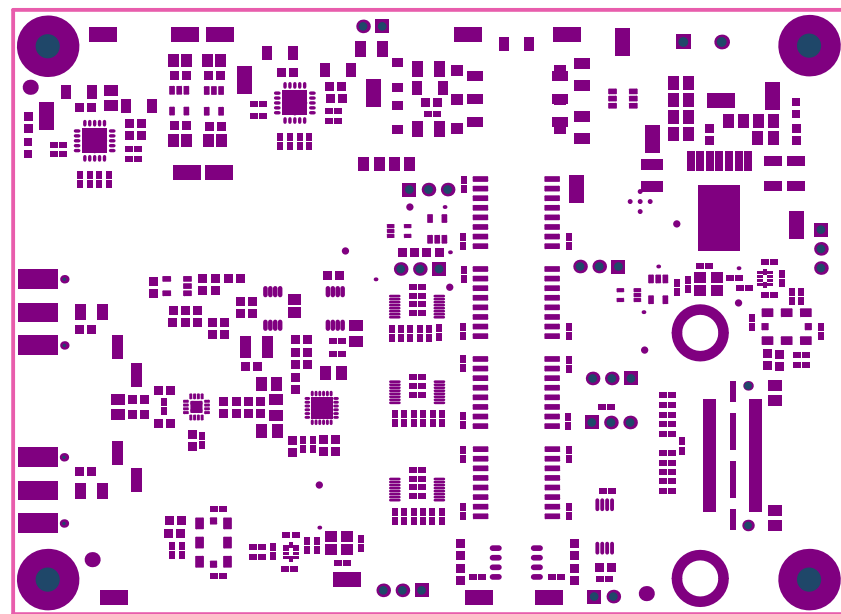


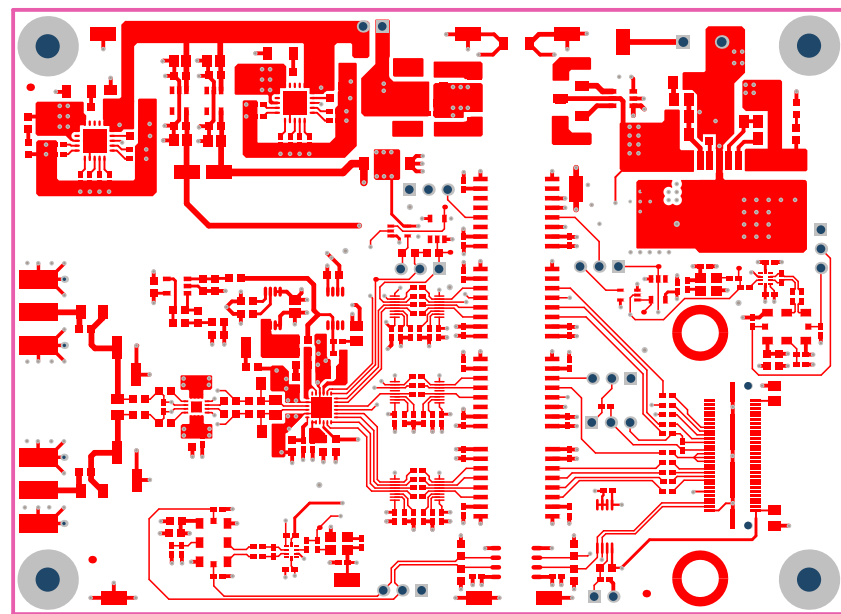
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01037		
Top Overlay	GENERATED : 12/7/2016 3:20:01 PM	TEXAS INSTRUMENTS	



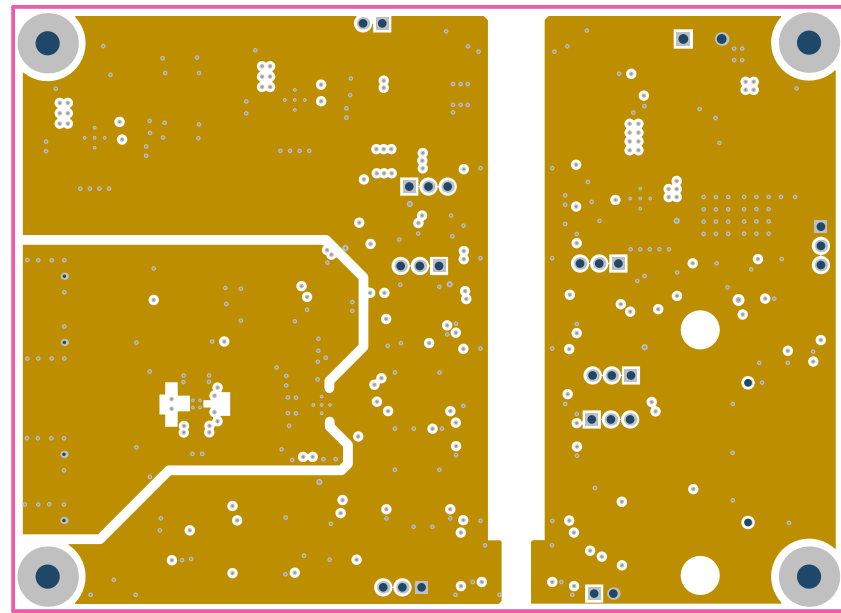
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDA-01037		
Top Paste	GENERATED : 12/7/2016 3:20:02 PM	TEXAS INSTRUMENTS	



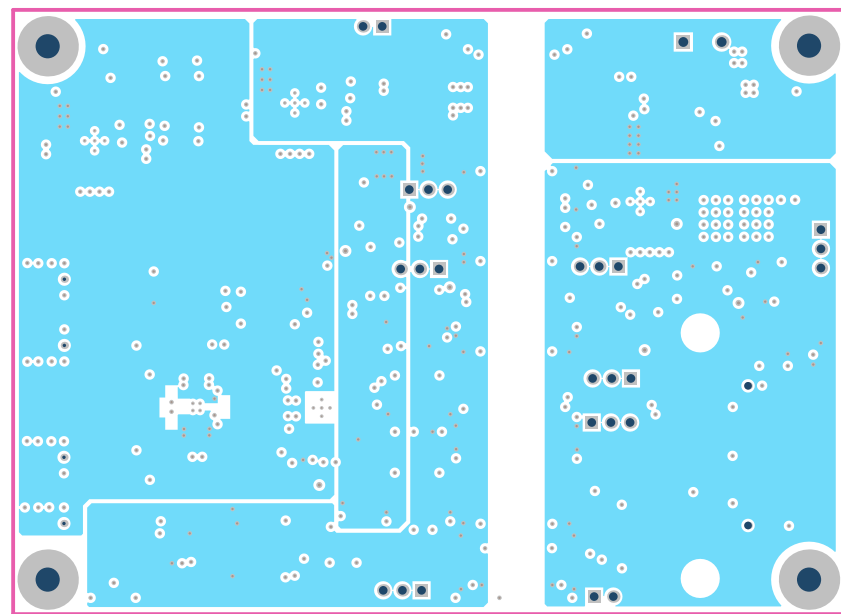
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01037		
Top Solder Mask	GENERATED : 12/7/2016 3:20:03 PM	TEXAS INSTRUMENTS	



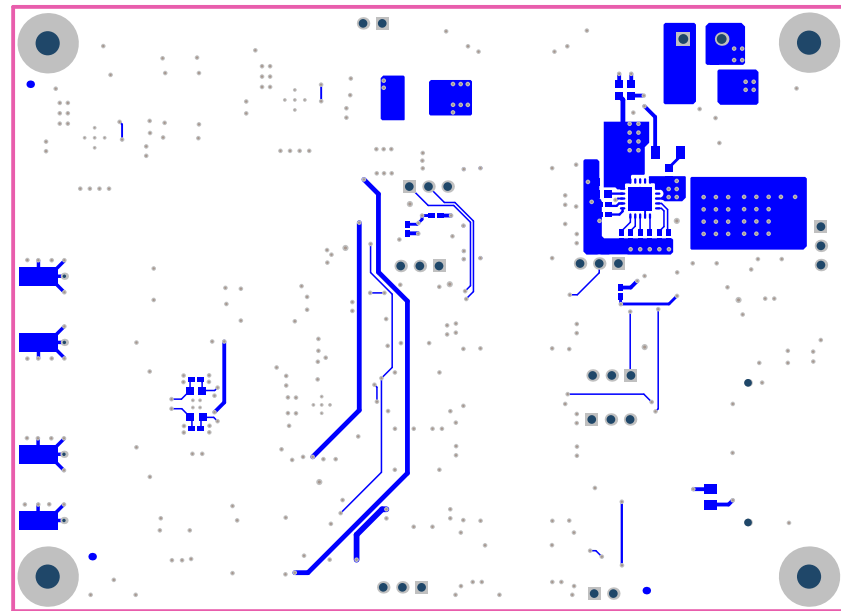
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01037		
Top Layer	GENERATED : 12/7/2016 3:20:04 PM	TEXAS INSTRUMENTS	



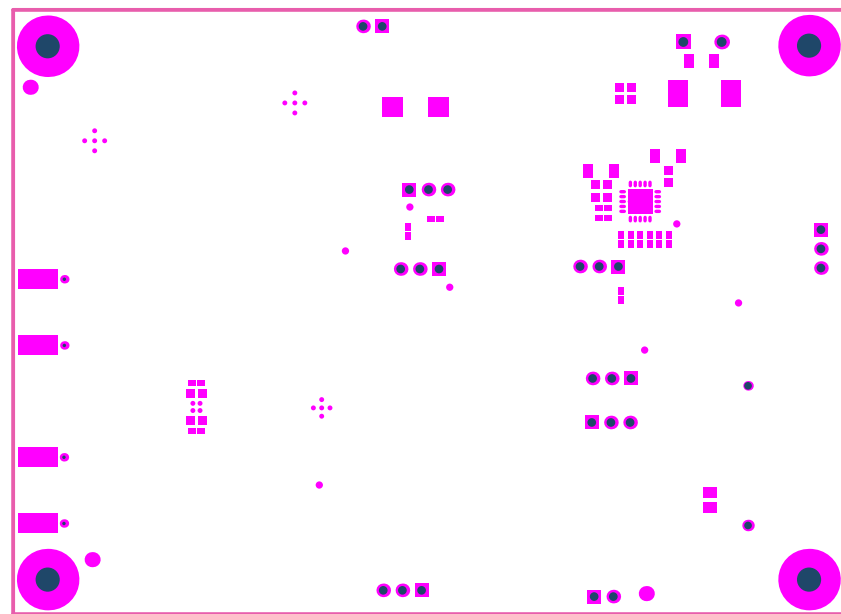
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-01037		
GND	GENERATED : 12/7/2016 3:20:05 PM	TEXAS INSTRUMENTS	



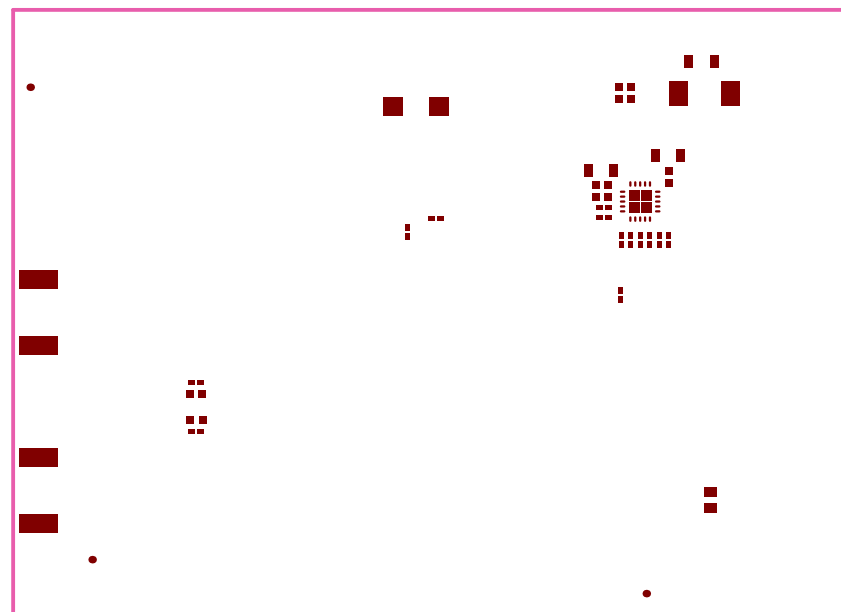
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = PWR	TID #: TIDA-01037		
PWR	GENERATED : 12/7/2016 3:20:06 PM	TEXAS INSTRUMENTS	



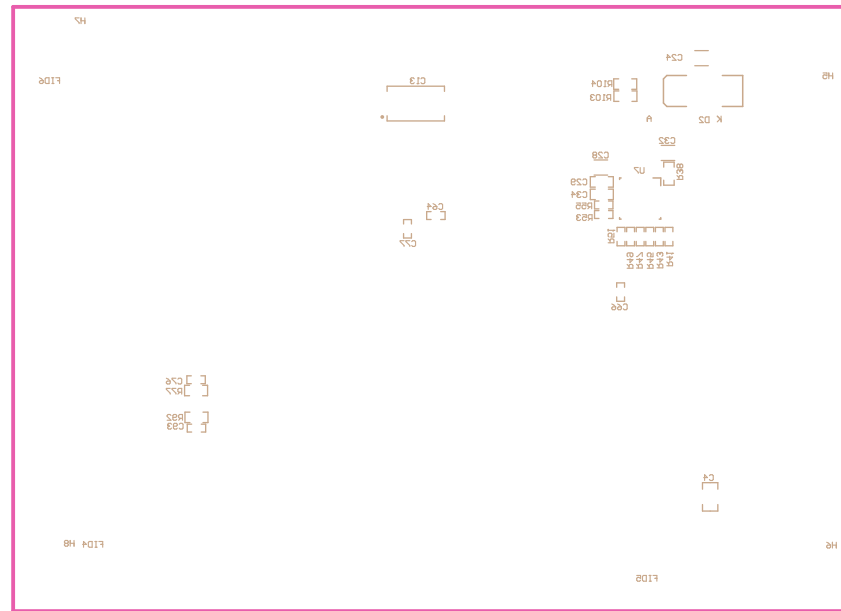
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01037		
Bottom Layer	GENERATED : 12/7/2016 3:20:06 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01037		
Bottom Solder Mask	GENERATED : 12/7/2016 3:20:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDA-01037		
Bottom Paste	GENERATED : 12/7/2016 3:20:08 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01037		
Bottom Overlay	GENERATED : 12/7/2016 3:20:09 PM	TEXAS INSTRUMENTS	

Layer Name	Server Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR4-High Tg
GNL	(.G1)	1.4mil	FR4-High Tg
DLR	(.G2)	1.4mil	FR4-High Tg
Bottom Layer	(.GBL)	1.4mil	FR4-High Tg
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
105MM X 80MM

Number of Layers : 4
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 7.5 MIL
 MIN. VIA DRILL SIZE: 7.874 MIL

MINIMUM ANNULAR RING 5.9055 MIL EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-408 FR-4 High Tg OTHER _____

THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)

INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG

IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

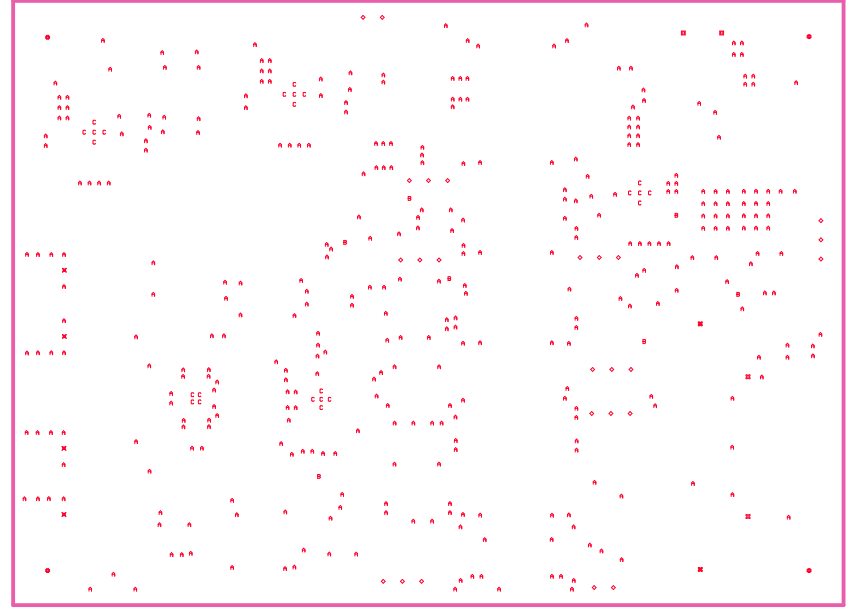
UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES NO

MICROSECTION: YES IMPEDANCE CONTROL: YES NO

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURER'S UL: RAIL METAL SILK



Symbol	Count	Hole Size	Plated	Hole Type
⊗	2	40.00mil (1.016mm)	NPTH	Round
⊠	2	51.18mil (1.300mm)	PTH	Round
⊗	2	173.23mil (4.400mm)	NPTH	Round
⊗	4	18.00mil (0.457mm)	PTH	Round
⊕	4	125.98mil (3.200mm)	PTH	Round
B	7	16.00mil (0.406mm)	PTH	Round
C	24	7.87mil (0.200mm)	PTH	Round
◇	25	45.28mil (1.150mm)	PTH	Round
A	360	12.00mil (0.305mm)	PTH	Round
	430 Total			

Drill Table

FOR 7.874MIL DRILL +0/-7.874MIL
 FOR 12MIL DRILL +0/-12MIL
 FOR 16MIL DRILL +0/-16MIL
 FOR PTH DRILL +/-3MIL
 FOR NPTH DRILL +/-2MIL

NOTE :
 Only 7.874 mil ,16 mil and 18 mil VIAS are not tented.



PROJECT TITLE:
 20-bit,High SNR DAQ with Host Generated Sample Clock and Low Jitter Isolator

DESIGNED FOR:
 Public Release

FILE NAME:
 TIDA-01037-E2.PcbDoc

ENGINEER:
 ANBU MANI / Harsh

LAYOUT BY:
 Avinash N

SCALE: 1,00

ALTIM DESIGNER VERSION:
 16.1.9.221

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01037		
Drill Drawing	GENERATED : 12/7/2016 3:20:11 PM	TEXAS INSTRUMENTS	

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01037	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01037		
Board Dimensions	GENERATED : 12/7/2016 3:20:13 PM	TEXAS INSTRUMENTS	

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